Preferred Device

## **Surface Mount Ultrafast Power Rectifiers**

Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes in surface mount applications where compact size and weight are critical to the system.

#### **Features**

- Pb-Free Package is Available
- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- Low Forward Voltage Drop (1.20 Volts Max @ 2.0 A, T<sub>I</sub> = 150°C)

#### **Mechanical Characteristics**

- Case: Epoxy, Molded
- Weight: 95 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	600	V
Average Rectified Forward Current	I <sub>F(AV)</sub>	2.0 @ T <sub>L</sub> = 125°C	Α
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I <sub>FSM</sub>	35	Α
Operating Junction Temperature	TJ	-65 to +175	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



ON Semiconductor®

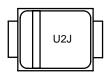
http://onsemi.com

# ULTRAFAST RECTIFIERS 2 AMPERES 600 VOLTS



SMB CASE 403A

#### **MARKING DIAGRAM**



U2J= Device Code

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MURS260T3	SMB	2500/Tape & Reel
MURS260T3G	SMB (Pb-Free)	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

#### THERMAL CHARACTERISTICS

Characteristic		Value	Unit
Thermal Resistance, Junction–to–Lead (T <sub>L</sub> = 25°C)	$R_{ hetaJL}$	13	°C/W

#### **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 1) $(i_F = 2.0 \text{ A}, T_J = 25^{\circ}\text{C})$ $(i_F = 2.0 \text{ A}, T_J = 150^{\circ}\text{C})$	V <sub>F</sub>	1.45 1.20	V
Maximum Instantaneous Reverse Current (Note 1) (Rated DC Voltage, $T_J = 25$ °C) (Rated DC Voltage, $T_J = 150$ °C)	i <sub>R</sub>	5.0 150	μΑ
Maximum Reverse Recovery Time $ (i_F = 1.0 \text{ A, di/dt} = 50 \text{ A/}\mu\text{s}) $ $ (i_F = 0.5 \text{ A, i}_R = 1.0 \text{ A, I}_R \text{ to } 0.25 \text{ A}) $	t <sub>rr</sub>	75 50	ns
Maximum Forward Recovery Time (i <sub>F</sub> = 1.0 A, di/dt = 100 A/μs, Rec. to 1.0 V)	t <sub>fr</sub>	50	ns

<sup>1.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

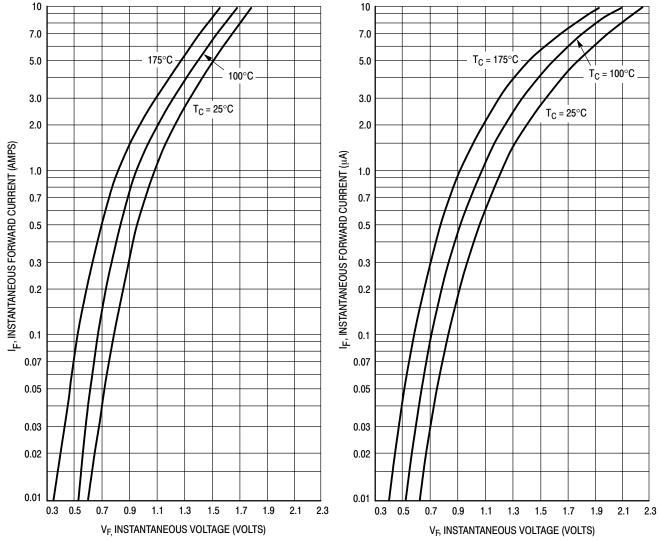
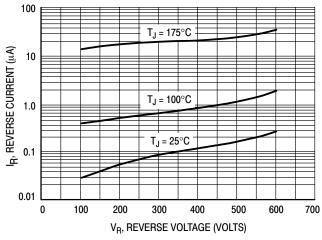
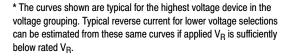


Figure 1. Typical Forward Voltage Figure 2. Maximum Forward Voltage







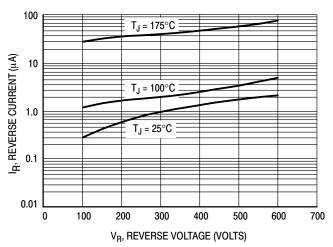


Figure 4. Maximum Reverse Current

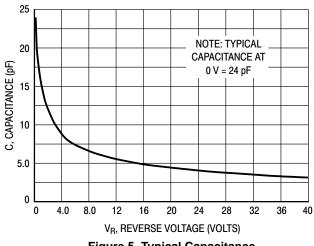


Figure 5. Typical Capacitance

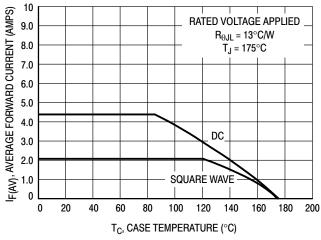


Figure 6. Current Derating, Case

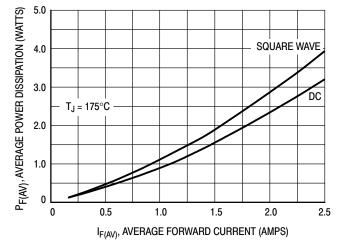
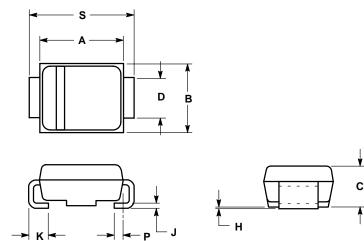


Figure 7. Power Dissipation

#### PACKAGE DIMENSIONS

**SMB** DO-214AA CASE 403A-03 ISSUE D

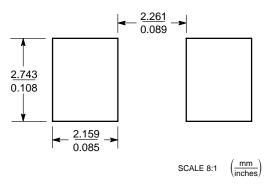


#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
  D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.160	0.180	4.06	4.57	
В	0.130	0.150	3.30	3.81	
С	0.075	0.095	1.90	2.41	
D	0.077	0.083	1.96	2.11	
Н	0.0020	0.0060	0.051	0.152	
J	0.006	0.012	0.15	0.30	
K	0.030	0.050	0.76	1.27	
P	0.020 REF		0.51 REF		
S	0.205	0.220	5.21	5.59	

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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